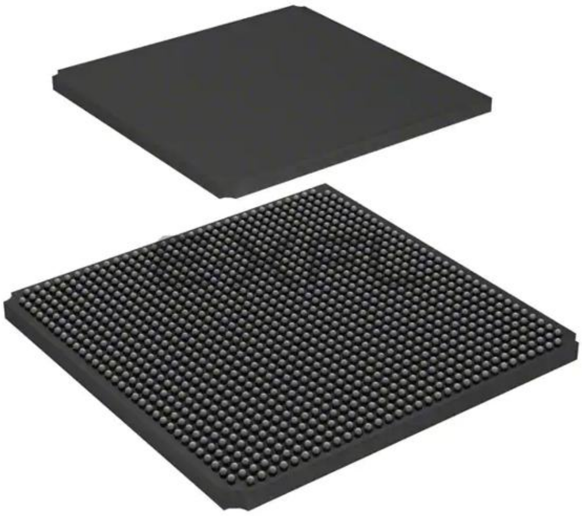
Lattice Semiconductor Corporation - LFE2M70SE-7FN1152C Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Not For New Designs
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	436
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-7fn1152c

LatticeECP2/M Family Data Sheet
Introduction

July 2012 **Data Sheet DS1006**

Features

- **High Logic Density for System Integration**
  - 6K to 95K LUTs
  - 90 to 583 I/Os
- **Embedded SERDES (LatticeECP2M Only)**
  - Data Rates 250 Mbps to 3.125 Gbps
  - Up to 16 channels per device PCI Express, Ethernet (1GbE, SGMII), OBSAI, CPRI and Serial RapidIO.
- **sysDSP™ Block**
  - 3 to 42 blocks for high performance multiply and accumulate
  - Each block supports
    - One 36x36, four 18x18 or eight 9x9 multipliers
- **Flexible Memory Resources**
  - 55Kbits to 5308Kbits sysMEM™ Embedded Block RAM (EBR)
    - 18Kbit block
    - Single, pseudo dual and true dual port
    - Byte Enable Mode support
  - 12K to 202Kbits distributed RAM
    - Single port and pseudo dual port
- **sysCLOCK Analog PLLs and DLLs**
  - Two GPLLs and up to six SPLLs per device
    - Clock multiply, divide, phase & delay adjust
    - Dynamic PLL adjustment
  - Two general purpose DLLs per device
- **Pre-Engineered Source Synchronous I/O**
  - DDR registers in I/O cells
  - Dedicated gearing logic
  - Source synchronous standards support
    - SPI4.2, SFI4 (DDR Mode), XGMII
    - High Speed ADC/DAC devices
  - Dedicated DDR and DDR2 memory support
    - DDR1: 400 (200MHz) / DDR2: 533 (266MHz)
  - Dedicated DQS support
- **Programmable sysI/O™ Buffer Supports Wide Range Of Interfaces**
  - LVTTL and LVCMOS 33/25/18/15/12
  - SSTL 3/2/18 I, II
  - HSTL15 I and HSTL18 I, II
  - PCI and Differential HSTL, SSTL
  - LVDS, RSDS, Bus-LVDS, MLVDS, LVPECL
- **Flexible Device Configuration**
  - 1149.1 Boundary Scan compliant
  - Dedicated bank for configuration I/Os
  - SPI boot flash interface
  - Dual boot images supported
  - TransFR™ I/O for simple field updates
  - Soft Error Detect macro embedded
- **Optional Bitstream Encryption (LatticeECP2/M "S" Versions Only)**
- **System Level Support**
  - ispTRACY™ internal logic analyzer capability
  - On-chip oscillator for initialization & general use
  - 1.2V power supply

Table 1-1. LatticeECP2 (Including "S-Series") Family Selection

Device	ECP2-6	ECP2-12	ECP2-20	ECP2-35	ECP2-50	ECP2-70
LUTs (K)	6	12	21	32	48	68
Distributed RAM (Kbits)	12	24	42	64	96	136
EBR SRAM (Kbits)	55	221	276	332	387	1032
EBR SRAM Blocks	3	12	15	18	21	60
sysDSP Blocks	3	6	7	8	18	22
18x18 Multipliers	12	24	28	32	72	88
GPLL + SPLL + DLL	2+0+2	2+0+2	2+0+2	2+0+2	2+2+2	2+4+2
Maximum Available I/O	190	297	402	450	500	583
Packages and I/O Combinations						
144-pin TQFP (20 x 20 mm)	90	93				
208-pin PQFP (28 x 28 mm)		131	131			
256-ball fpBGA (17 x 17 mm)	190	193	193			
484-ball fpBGA (23 x 23 mm)		297	331	331	339	
672-ball fpBGA (27 x 27 mm)			402	450	500	500
900-ball fpBGA (31 x 31 mm)						583

LatticeECP2/M Family Data Sheet
Architecture

September 2013 **Data Sheet DS1006**

Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sysDSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

- MULT (Multiply)
- MAC (Multiply, Accumulate)
- MULTADDSUB (Multiply, Addition/Subtraction)
- MULTADDSUBSUM (Multiply, Addition/Subtraction, Accumulate)

The number of elements available on each block depends in the width selected from the three available options x9, x18, and x36. A number of these elements are concatenated for highly parallel implementations of DSP functions. Table 2-7 shows the capabilities of the block.

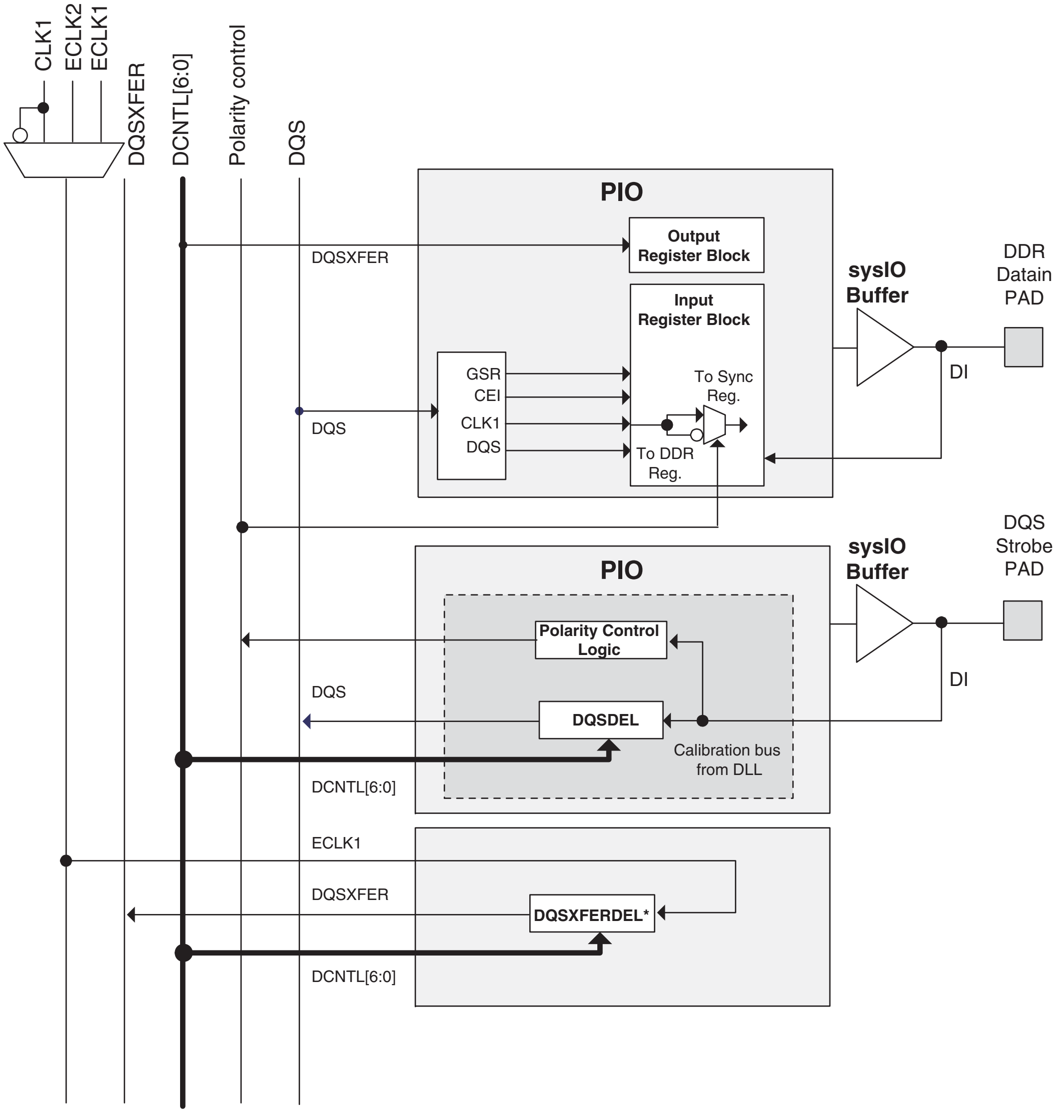
Table 2-7. Maximum Number of Elements in a Block

Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADDSUB	4	2	—
MULTADDSUBSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as a shift register from previous operand registers. By selecting “dynamic operation” the following operations are possible:

- In the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle.
- In the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.
- The loading of operands can switch between parallel and serial operations.

Figure 2-36. DQS Local Bus



*DQSXFERDEL shifts ECLK1 by 90% and is not associated with a particular PIO.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relationship between the incoming delayed DQS strobe and the internal system clock (during the READ cycle) is unknown.

The LatticeECP2/M family contains dedicated circuits to transfer data between these domains. To prevent set-up and hold violations, at the domain transfer between DQS (delayed) and the system clock, a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories, DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects the first DQS rising edge after the preamble state. This signal is used to control the polarity of the clock to the synchronizing registers.

LatticeECP2M Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply Current	ECP2M20	25	mA
		ECP2M35	50	mA
		ECP2M50	85	mA
		ECP2M70	100	mA
		ECP2M100	100	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2M20	24	mA
		ECP2M35	24	mA
		ECP2M50	24	mA
		ECP2M70	24	mA
		ECP2M100	24	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	All Devices	0.5	mA
I_{CCSPLL}	GPLL Power Supply Current (per SPLL)	All Devices	0.5	mA
I_{CCIO}	Bank Power Supply Current (Per Bank)	ECP2M20	2	mA
		ECP2M35	2	mA
		ECP2M50	2	mA
		ECP2M70	2	mA
		ECP2M100	2	mA
I_{CCJ}	V_{CCJ} Power Supply Current	All Devices	3	mA

1. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a “blank” configuration data file.
5. T_J = 25°C, power supplies at normal voltage.

SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

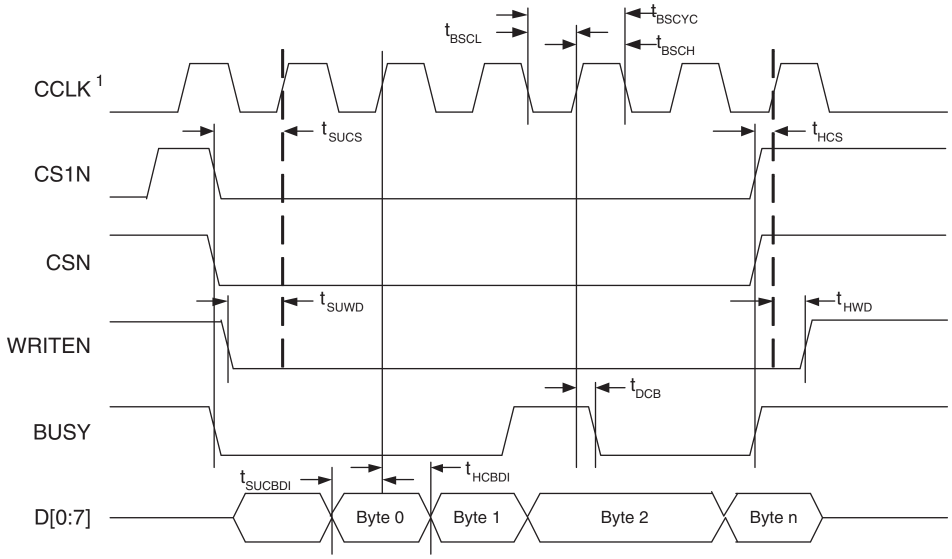
1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25°C and 1.2V.

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay[1]	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port[2]				
t_{CFGX}	INITN High to CCLK Low	—	1	µs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

Figure 3-15. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-16. sysCONFIG Slave Serial Port Timing

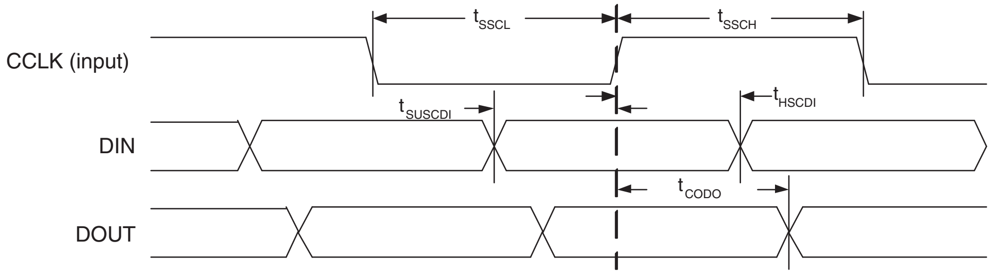
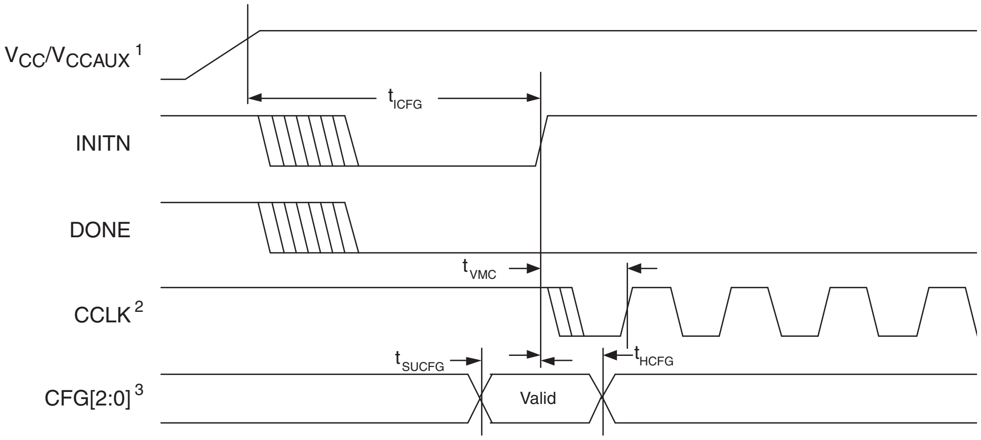


Figure 3-17. Power-On-Reset (POR) Timing



1. Time taken from V_{CC} or V_{CCAUX}, whichever is the last to reach its V_{MIN}.
2. Device is in a Master Mode.
3. The CFG pins are normally static (hard wired).

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W19	CFG2	8			CFG2	8		
V19	CFG1	8			CFG1	8		
V20	PROGRAMN	8			PROGRAMN	8		
W20	CFG0	8			CFG0	8		
U22	PR28B	8	D1	C	PR42B	8	D1	C
V22	INITN	8			INITN	8		
R16	PR30B	8	WRITEN	C	PR44B	8	WRITEN	C
GNDIO	GNDIO8	-			GNDIO8	-		
W22	CCLK	8			CCLK	8		
R17	PR30A	8	CS1N	T	PR44A	8	CS1N	T
V21	DONE	8			DONE	8		
VCCIO	VCCIO8	8			VCCIO8	8		
U19	PR29B	8	CSN	C	PR43B	8	CSN	C
T17	PR26B	8	D5	C	PR40B	8	D5	C
U20	PR29A	8	D0/SPIFASTN	T	PR43A	8	D0/SPIFASTN	T
U21	PR28A	8	D2	T	PR42A	8	D2	T
GNDIO	GNDIO8	-			GNDIO8	-		
T18	PR26A	8	D6	T	PR40A	8	D6	T
T20	PR27B	8	D3	C	PR41B	8	D3	C
T21	PR25B	8	D7/SPID0	C	PR39B	8	D7/SPID0	C
T19	PR27A	8	D4	T	PR41A	8	D4	T
VCCIO	VCCIO8	8			VCCIO8	8		
T22	PR25A	8	DI/CSSPI0N	T	PR39A	8	DI/CSSPI0N	T
R18	PR24B	8	DOUT/CSON	C	PR38B	8	DOUT/CSON	C
R19	PR24A	8	BUSY/SISPI	T	PR38A	8	BUSY/SISPI	T
-	-	-			VCCIO3	3		
GNDIO	GNDIO3	-			GNDIO3	-		
P18	PR22B	3		C (LVDS)*	PR32B	3	RDQ34	C (LVDS)*
R22	PR23B	3		C	PR33B	3	RDQ34	C
P19	PR22A	3		T (LVDS)*	PR32A	3	RDQ34	T (LVDS)*
R21	PR23A	3		T	PR33A	3	RDQ34	T
VCCIO	VCCIO3	3			VCCIO3	3		
R20	PR21B	3	RLM0_GPLLC_FB_A	C	PR31B	3	RLM0_GPLLC_FB_A/RDQ34	C
P22	PR21A	3	RLM0_GPLLT_FB_A	T	PR31A	3	RLM0_GPLLT_FB_A/RDQ34	T
P21	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*
N21	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*
N17	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
N22	PR18B	3	RLM0_GDLLC_FB_A	C	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C
M22	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
N20	PR18A	3	RLM0_GDLLT_FB_A	T	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T
M21	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*
N19	NC	-			PR26B	3	RDQ25	C
-	-	-			VCCIO3	3		

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

	LFE2-35E/SE				LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N16	VCCIO3	3			VCCIO3	3		
P16	VCCIO3	3			VCCIO3	3		
R14	VCCIO4	4			VCCIO4	4		
T12	VCCIO4	4			VCCIO4	4		
T13	VCCIO4	4			VCCIO4	4		
T14	VCCIO4	4			VCCIO4	4		
R9	VCCIO5	5			VCCIO5	5		
T10	VCCIO5	5			VCCIO5	5		
T11	VCCIO5	5			VCCIO5	5		
T9	VCCIO5	5			VCCIO5	5		
N7	VCCIO6	6			VCCIO6	6		
P7	VCCIO6	6			VCCIO6	6		
P8	VCCIO6	6			VCCIO6	6		
R8	VCCIO6	6			VCCIO6	6		
J8	VCCIO7	7			VCCIO7	7		
K7	VCCIO7	7			VCCIO7	7		
L7	VCCIO7	7			VCCIO7	7		
M7	VCCIO7	7			VCCIO7	7		
P15	VCCIO8	8			VCCIO8	8		
R15	VCCIO8	8			VCCIO8	8		
A22	GND	-			GND	-		
AA19	GND	-			GND	-		
AA4	GND	-			GND	-		
AB1	GND	-			GND	-		
AB22	GND	-			GND	-		
B19	GND	-			GND	-		
B4	GND	-			GND	-		
C14	GND	-			GND	-		
C9	GND	-			GND	-		
D2	GND	-			GND	-		
D21	GND	-			GND	-		
F17	GND	-			GND	-		
F6	GND	-			GND	-		
H10	GND	-			GND	-		
H11	GND	-			GND	-		
H12	GND	-			GND	-		
H13	GND	-			GND	-		
J14	GND	-			GND	-		
J20	GND	-			GND	-		
J3	GND	-			GND	-		
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
Y21	PB64A	4	VREF2_4/BDQ60	T	PB73A	4	VREF2_4/BDQ69	T
AB23	PB64B	4	VREF1_4/BDQ60	C	PB73B	4	VREF1_4/BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AD24	CFG2	8			CFG2	8		
W20	CFG1	8			CFG1	8		
AC24	CFG0	8			CFG0	8		
V19	PROGRAMN	8			PROGRAMN	8		
AA22	CCLK	8			CCLK	8		
AB24	INITN	8			INITN	8		
AD25	DONE	8			DONE	8		
GND	GNDIO8	-			GNDIO8	-		
W21	PR44B	8	WRITEN	C	PR58B	8	WRITEN	C
Y22	PR44A	8	CS1N	T	PR58A	8	CS1N	T
AC25	PR43B	8	CSN	C	PR57B	8	CSN	C
AB25	PR43A	8	D0/SPIFASTN	T	PR57A	8	D0/SPIFASTN	T
VCCIO	VCCIO8	8			VCCIO8	8		
AD26	PR42B	8	D1	C	PR56B	8	D1	C
AC26	PR42A	8	D2	T	PR56A	8	D2	T
Y23	PR41B	8	D3	C	PR55B	8	D3	C
GND	GNDIO8	-			GNDIO8	-		
W22	PR41A	8	D4	T	PR55A	8	D4	T
AA25	PR40B	8	D5	C	PR54B	8	D5	C
AB26	PR40A	8	D6	T	PR54A	8	D6	T
W23	PR39B	8	D7/SPID0	C	PR53B	8	D7/SPID0	C
VCCIO	VCCIO8	8			VCCIO8	8		
V22	PR39A	8	DI/CSSPI0N	T	PR53A	8	DI/CSSPI0N	T
Y24	PR38B	8	DOUT/CSON	C	PR52B	8	DOUT/CSON	C
Y25	PR38A	8	BUSY/SISPI	T	PR52A	8	BUSY/SISPI	T
W24	PR37B	3	RDQ34	C	PR51B	3	RDQ48	C
GND	GNDIO3	-			GNDIO3	-		
V23	PR37A	3	RDQ34	T	PR51A	3	RDQ48	T
AA26	PR36B	3	RDQ34	C (LVDS)*	PR50B	3	RDQ48	C (LVDS)*
Y26	PR36A	3	RDQ34	T (LVDS)*	PR50A	3	RDQ48	T (LVDS)*
U21	PR35B	3	RDQ34	C	PR49B	3	RDQ48	C
VCCIO	VCCIO3	3			VCCIO3	3		
U19	PR35A	3	RDQ34	T	PR49A	3	RDQ48	T
W25	PR34B	3	RDQ34	C (LVDS)*	PR48B	3	RDQ48	C (LVDS)*
W26	PR34A	3	RDQS34	T (LVDS)*	PR48A	3	RDQS48	T (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
V24	PR33B	3	RDQ34	C	PR47B	3	RDQ48	C
V25	PR33A	3	RDQ34	T	PR47A	3	RDQ48	T
V26	PR32B	3	RDQ34	C (LVDS)*	PR46B	3	RDQ48	C (LVDS)*
U26	PR32A	3	RDQ34	T (LVDS)*	PR46A	3	RDQ48	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
U22	PR31B	3	RLM0_GPLLC_FB_A/RDQ34	C	PR45B	3	RLM0_GPLLC_FB_A/RDQ48	C
U23	PR31A	3	RLM0_GPLLT_FB_A/RDQ34	T	PR45A	3	RLM0_GPLLT_FB_A/RDQ48	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
U24	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*	PR44B	3	RLM0_GPLLC_IN_A**/RDQ48	C (LVDS)*
U25	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*	PR44A	3	RLM0_GPLLT_IN_A**/RDQ48	T (LVDS)*
R20	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
P18	VCC	3			VCCPLL	3		
T19	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C	PR42B	3	RLM0_GDLLC_FB_A/RDQ39	C
U20	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T	PR42A	3	RLM0_GDLLT_FB_A/RDQ39	T
GND	GNDIO3	-			GNDIO3	-		
T25	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*	PR41B	3	RLM0_GDLLC_IN_A**/RDQ39	C (LVDS)*
T26	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*	PR41A	3	RLM0_GDLLT_IN_A**/RDQ39	T (LVDS)*
T20	PR26B	3	RDQ25	C	PR40B	3	RDQ39	C
T22	PR26A	3	RDQ25	T	PR40A	3	RDQ39	T
VCCIO	VCCIO3	3			VCCIO3	3		
R26	PR25B	3	RDQ25	C (LVDS)*	PR39B	3	RDQ39	C (LVDS)*
R25	PR25A	3	RDQS25***	T (LVDS)*	PR39A	3	RDQS39***	T (LVDS)*
R22	NC	-			PR38B	3	RDQ39	C
GND	GNDIO3	-			GNDIO3	-		
T21	NC	-			PR38A	3	RDQ39	T
P26	NC	-			NC	-		
P25	NC	-			NC	-		
R24	NC	-			NC	-		
VCCIO	VCCIO3	3			VCCIO3	3		
R23	NC	-			NC	-		
P20	NC	-			NC	-		
R19	NC	-			NC	-		
P21	NC	-			PR34B	3	RDQ31	C
GND	GNDIO3	-			GNDIO3	-		
P19	NC	-			PR34A	3	RDQ31	T
P23	NC	-			PR33B	3	RDQ31	C (LVDS)*
P22	NC	-			PR33A	3	RDQ31	T (LVDS)*
N22	NC	-			PR32B	3	RDQ31	C
VCCIO	VCCIO3	3			VCCIO3	3		
R21	NC	-			PR32A	3	RDQ31	T
N26	NC	-			PR31B	3	RDQ31	C (LVDS)*
N25	NC	-			PR31A	3	RDQS31	T (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
N19	PR24B	3	RDQ25	C	PR30B	3	RDQ31	C
N20	PR24A	3	RDQ25	T	PR30A	3	RDQ31	T
M26	PR23B	3	RDQ25	C (LVDS)*	PR29B	3	RDQ31	C (LVDS)*
M25	PR23A	3	RDQ25	T (LVDS)*	PR29A	3	RDQ31	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
N18	PR22B	3	VREF2_3/RDQ25	C	PR28B	3	VREF2_3/RDQ31	C
N21	PR22A	3	VREF1_3/RDQ25	T	PR28A	3	VREF1_3/RDQ31	T
L26	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*	PR27B	3	PCLKC3_0/RDQ31	C (LVDS)*
L25	PR21A	3	PCLKT3_0/RDQ25	T (LVDS)*	PR27A	3	PCLKT3_0/RDQ31	T (LVDS)*
N24	PR19B	2	PCLKC2_0/RDQ16	C	PR25B	2	PCLKC2_0/RDQ22	C
M23	PR19A	2	PCLKT2_0/RDQ16	T	PR25A	2	PCLKT2_0/RDQ22	T

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
L11	GND	-		
L12	GND	-		
L13	GND	-		
M10	GND	-		
M11	GND	-		
M12	GND	-		
M13	GND	-		
N10	GND	-		
N11	GND	-		
N12	GND	-		
N13	GND	-		
N15	GND	-		
N20	GND	-		
N3	GND	-		
N8	GND	-		
P14	GND	-		
P9	GND	-		
R10	GND	-		
R13	GND	-		
T19	GND	-		
T4	GND	-		
W16	GND	-		
W2	GND	-		
W21	GND	-		
W7	GND	-		
Y10	GND	-		
Y13	GND	-		
Y15	NC	-		
W15	NC	-		
AB20	NC	-		
AB21	NC	-		
AA21	NC	-		
AA20	NC	-		
AB19	NC	-		
AB18	NC	-		
Y22	NC	-		
Y21	NC	-		
Y17	NC	-		
Y18	NC	-		
Y16	NC	-		
W17	NC	-		
Y19	NC	-		
Y20	NC	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
Y22	PR60B	3		C	PR81B	3	RDQ82	C
Y23	PR60A	3		T	PR81A	3	RDQ82	T
AB26	NC	-			PR80B	3	RDQ82	C (LVDS)*
AB27	NC	-			PR80A	3	RDQ82	T (LVDS)*
-	-	-			VCCIO3	3		
Y24	NC	-			PR79B	3	RDQ82	C
Y25	NC	-			PR79A	3	RDQ82	T
AA29	NC	-			PR78B	3	RDQ82	C (LVDS)*
Y28	NC	-			PR78A	3	RDQ82	T (LVDS)*
Y30	NC	-			PR76B	3	RDQ73	C
Y29	NC	-			PR76A	3	RDQ73	T
-	-	-			GNDIO3	-		
-	-	-			-	-		
W22	NC	-			PR75B	3	RDQ73	C (LVDS)*
V22	NC	-			PR75A	3	RDQ73	T (LVDS)*
Y27	NC	-			PR74B	3	RDQ73	C
-	-	-			VCCIO3	3		
Y26	NC	-			PR74A	3	RDQ73	T
W30	NC	-			PR73B	3	RDQ73	C (LVDS)*
W29	NC	-			PR73A	3	RDQS73	T (LVDS)*
-	-	-			GNDIO3	-		
W25	NC	-			PR72B	3	RDQ73	C
W26	NC	-			PR72A	3	RDQ73	T
U29	PR59B	3		C (LVDS)*	PR71B	3	RDQ73	C (LVDS)*
V29	PR59A	3		T (LVDS)*	PR71A	3	RDQ73	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
V30	PR58B	3		C	PR70B	3	RDQ73	C
U30	PR58A	3		T	PR70A	3	RDQ73	T
W27	PR57B	3		C (LVDS)*	PR69B	3	RDQ73	C (LVDS)*
W28	PR57A	3		T (LVDS)*	PR69A	3	RDQ73	T (LVDS)*
V24	PR55B	3	RDQ52	C	PR67B	3	RDQ64	C
V25	PR55A	3	RDQ52	T	PR67A	3	RDQ64	T
GNDIO	GNDIO3	-			GNDIO3	-		
U28	PR54B	3	RDQ52	C (LVDS)*	PR66B	3	RDQ64	C (LVDS)*
U27	PR54A	3	RDQ52	T (LVDS)*	PR66A	3	RDQ64	T (LVDS)*
U23	PR53B	3	RDQ52	C	PR65B	3	RDQ64	C
V23	PR53A	3	RDQ52	T	PR65A	3	RDQ64	T
VCCIO	VCCIO3	3			VCCIO3	3		
V26	PR52B	3	RDQ52	C (LVDS)*	PR64B	3	RDQ64	C (LVDS)*
U26	PR52A	3	RDQS52	T (LVDS)*	PR64A	3	RDQS64	T (LVDS)*
U25	PR51B	3	RDQ52	C	PR63B	3	RDQ64	C
GNDIO	GNDIO3	-			GNDIO3	-		
U24	PR51A	3	RDQ52	T	PR63A	3	RDQ64	T
T30	PR50B	3	RDQ52	C (LVDS)*	PR62B	3	RDQ64	C (LVDS)*
R30	PR50A	3	RDQ52	T (LVDS)*	PR62A	3	RDQ64	T (LVDS)*
T23	PR49B	3	RDQ52	C	PR61B	3	RDQ64	C
VCCIO	VCCIO3	3			VCCIO3	3		
T22	PR49A	3	RDQ52	T	PR61A	3	RDQ64	T

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
-	-	-			VCCIO2	2		
H23	NC	-			PR15B	2	RDQ15	C (LVDS)*
H24	NC	-			PR15A	2	RDQS15	T (LVDS)*
D28	NC	-			PR14B	2	RDQ15	C
-	-	-			GNDIO2	-		
E28	NC	-			PR14A	2	RDQ15	T
G24	PR13B	2		C (LVDS)*	PR13B	2	RDQ15	C (LVDS)*
H25	PR13A	2		T (LVDS)*	PR13A	2	RDQ15	T (LVDS)*
D27	PR12B	2	RUM0_SPLLC_FB_A	C	PR12B	2	RUM0_SPLLC_FB_A/RDQ15	C
GNDIO	GNDIO2	-			VCCIO2	2		
E27	PR12A	2	RUM0_SPLLT_FB_A	T	PR12A	2	RUM0_SPLLT_FB_A/RDQ15	T
F26	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*
G25	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
F24	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C
VCCIO	VCCIO2	-			-	-		
GNDIO	GNDIO2	-			GNDIO2	-		
F25	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2			VCCIO2	2		
G23	XRES	-			XRES	1		
C30	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12		
A29	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T
B30	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12		
B29	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C
C27	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12		
A26	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T
A27	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12		
B26	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C
C26	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12		
B25	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C
C25	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12		
A25	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T
C29	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12		
B28	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C
C28	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12		
A28	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T
B24	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12		
E24	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C
D24	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T
C24	URC_SQ_VCCP	12			URC_SQ_VCCP	12		
A20	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T
C20	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B20	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C19	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A23	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C23	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B23	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C22	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B22	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K3	VCCIO7	7			VCCIO7	7		
M10	VCCIO7	7			VCCIO7	7		
M7	VCCIO7	7			VCCIO7	7		
N10	VCCIO7	7			VCCIO7	7		
N3	VCCIO7	7			VCCIO7	7		
P10	VCCIO7	7			VCCIO7	7		
R6	VCCIO7	7			VCCIO7	7		
AA25	VCCIO8	8			VCCIO8	8		
AD28	VCCIO8	8			VCCIO8	8		
AA10	VCCAUX	-			VCCAUX	-		
AA11	VCCAUX	-			VCCAUX	-		
AA20	VCCAUX	-			VCCAUX	-		
AA21	VCCAUX	-			VCCAUX	-		
K10	VCCAUX	-			VCCAUX	-		
K11	VCCAUX	-			VCCAUX	-		
K20	VCCAUX	-			VCCAUX	-		
K21	VCCAUX	-			VCCAUX	-		
L10	VCCAUX	-			VCCAUX	-		
L11	VCCAUX	-			VCCAUX	-		
L20	VCCAUX	-			VCCAUX	-		
L21	VCCAUX	-			VCCAUX	-		
Y10	VCCAUX	-			VCCAUX	-		
Y11	VCCAUX	-			VCCAUX	-		
Y20	VCCAUX	-			VCCAUX	-		
Y21	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A13	GND	-			GND	-		
A18	GND	-			GND	-		
A24	GND	-			GND	-		
A30	GND	-			GND	-		
A7	GND	-			GND	-		
AA14	GND	-			GND	-		
AA15	GND	-			GND	-		
AA16	GND	-			GND	-		
AA17	GND	-			GND	-		
AA24	GND	-			GND	-		
AA27	GND	-			GND	-		
AA4	GND	-			GND	-		
AB24	GND	-			GND	-		
AB7	GND	-			GND	-		
AD12	GND	-			GND	-		
AD19	GND	-			GND	-		
AD27	GND	-			GND	-		
AE22	GND	-			GND	-		
AE27	GND	-			GND	-		
AE4	GND	-			GND	-		
AE9	GND	-			GND	-		
AF14	GND	-			GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
H33	PR14B	2	RDQ15	C	PR14B	2	RDQ15	C
GNDIO	GNDIO2	-			GNDIO2	-		
H34	PR14A	2	RDQ15	T	PR14A	2	RDQ15	T
J30	PR13B	2	RDQ15	C (LVDS)*	PR13B	2	RDQ15	C (LVDS)*
J29	PR13A	2	RDQ15	T (LVDS)*	PR13A	2	RDQ15	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
J27	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*
J28	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
H31	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-			GNDIO2	-		
H32	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2			VCCIO2	2		
H30	XRES	1			XRES	1		
B33	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12		
C33	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T
B34	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12		
C32	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C
B32	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12		
A33	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T
C34	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12		
A32	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C
B31	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12		
A31	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C
D32	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12		
A30	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T
B30	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12		
C31	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C
D31	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12		
C30	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T
E29	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12		
E30	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C
D30	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T
D29	URC_SQ_VCCP	12			URC_SQ_VCCP	12		
C29	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T
D27	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
C28	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
B29	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A29	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
E28	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
A28	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
B28	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
A27	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
D26	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A26	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
B27	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
C27	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B26	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
C26	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
D28	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE					LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E23	PT82B	1		C	PT100B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
F23	PT82A	1		T	PT100A	1		T
F24	NC	-			PT99B	1		C
G23	NC	-			PT99A	1		T
D23	PT80B	1		C	PT98B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
D22	PT80A	1		T	PT98A	1		T
-	-	-			GNDIO1	-		
-	-	-			VCCIO1	1		
C21	PT79B	1		C	PT88B	1		C
D21	PT79A	1		T	PT88A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
B21	PT77B	1		C	PT86B	1		C
A21	PT77A	1		T	PT86A	1		T
F22	PT76B	1		C	PT85B	1		C
E22	PT76A	1		T	PT85A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
GNDIO	GNDIO1	-			-	-		
J22	NC	-			PT84B	1		C
G22	NC	-			PT84A	1		T
-	-	-			GNDIO1	-		
H22	PT72B	1		C	PT81B	1		C
K22	PT72A	1		T	PT81A	1		T
G21	PT71B	1		C	PT80B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
J21	PT71A	1		T	PT80A	1		T
H21	NC	-			PT79B	1		C
K21	NC	-			PT79A	1		T
D20	PT69B	1		C	PT78B	1		C
F20	PT69A	1		T	PT78A	1		T
C20	PT68B	1		C	PT77B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
E20	PT68A	1		T	PT77A	1		T
G20	PT67B	1		C	PT76B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
J20	PT67A	1		T	PT76A	1		T
A20	PT66B	1		C	PT75B	1		C
B20	PT66A	1		T	PT75A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
A19	PT63B	1		C	PT72B	1		C
B19	PT63A	1		T	PT72A	1		T
K20	PT62B	1		C	PT71B	1		C
H20	PT62A	1		T	PT71A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
L19	NC	-			PT70B	1		C
L20	NC	-			PT70A	1		T
E19	PT60B	1		C	PT69B	1		C
C18	PT60A	1		T	PT69A	1		T

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100E-5FN1152C	520	1.2V	-5	Lead-Free fpBGA	1152	COM	100
LFE2M100E-6FN1152C	520	1.2V	-6	Lead-Free fpBGA	1152	COM	100
LFE2M100E-7FN1152C	520	1.2V	-7	Lead-Free fpBGA	1152	COM	100
LFE2M100E-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	COM	100
LFE2M100E-6FN900C	416	1.2V	-6	Lead-Free fpBGA	900	COM	100
LFE2M100E-7FN900C	416	1.2V	-7	Lead-Free fpBGA	900	COM	100

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	IND	20
LFE2M20E-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	IND	20
LFE2M20E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	20
LFE2M20E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	IND	35
LFE2M35E-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	IND	35
LFE2M35E-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	IND	35
LFE2M35E-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	IND	35
LFE2M35E-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	IND	35
LFE2M35E-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50E-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50E-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50E-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50E-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50E-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70E-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70E-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70

LatticeECP2/M Family Data Sheet Revision History

September 2013 **Data Sheet DS1006**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
August 2006	01.1	Introduction	
			Updated Table 1-1 “LatticeECP2 Family Selection Guide”.
		Architecture	Updated Figure 2-2 “PFU Diagram”.
			Updated Figure 2-13 “Secondary Clock Regions ECP2-50”.
			Updated Figure 2-25 “PIC Diagram”.
			Updated Figure 2-26 “Input Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-28 “Output Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-30 “DQS Input Routing for Left and Right Edges”.
			Updated Figure 2-32 “Edge Clock, DLL Calibration and DQS Local Bus Distribution”.
			Table 2-15 Selectable Master Clock (CCLK) Frequencies - Removed frequencies 15, 20, 21, 22, 23, 30, 34, 41, 45, 51, 55, 60.
			Replaced “CLKINDEL” with “CLKO”.
			Updated SED section.
			Qualified device migration capability when using DQS banks for DDR interfaces.
		DC and Switching Characteristics	Added VCCPLL to the Recommended Operating Conditions table.
			Removed note 5 from “Hot Specifications” section.
			Added notes 7 and 8 to “Initialization Supply” Current table.
			Change note 6 - “...down to 95MHz” to “...down to 95MHz for DDR and 133MHz for DDR2” .
			New “Typical Building Block Function Performance” numbers.
			New External Switching Characteristics numbers.
			New Internal Switching Characteristics numbers.
			New Family Timing Adders numbers.
			Updated Timings for GPLLs, SPLLs and DLLs.
			Added sysCONFIG waveforms.
			Remove HSTL15D_II from sysIO Recommended Operating Conditions table.
			Updated Supply and Initialization Currents for ECP2-50.
		Pinout Information	Added VCCPLL to the Signal Descriptions table.
			Updated Logic Signal Connections tables to include 484-fpBGA for the ECP2-50.
			Added Logic Signal Connections tables for ECP2-12 devices.
			Updated Pin Information Summary table to include ECP2-12.
			Updated Power Supply and NC Connections table to include ECP2-12.
			Added note 2 to DDR Strobe (DQS) Pin table.
			Added Information on: PCI, DDR & SPI4.2 Capabilities of the device-Package combination.